LM74A SPI/MICROWIRE 12-Bit Plus Sign Temperature Sensor (LM74 in Die Form)

Check for Samples: LM74A

FEATURES

- **0.0625°C Temperature Resolution.**
- **Shutdown Mode Conserves Power between Temperature Reading**
- **SPI and MICROWIRE Bus Interface**
- **LM74 is also Available in a 5-Bump DSBGA and 8-pin SOIC**

APPLICATIONS

- **System Thermal Management**
- **Personal Computers**
- **Disk Drives**
- **Office Electronics**
- **Electronic Test Equipment**

DESCRIPTION

The LM74A is a temperature sensor, Delta-Sigma analog-to-digital converter with an SPI and MICROWIRE compatible interface in die form. The host can query the LM74A at any time to read temperature. A shutdown mode decreases power consumption to less than 10 µA. This mode is useful in systems where low average power consumption is critical.

This particular data sheet applies to the LM74 in die form. The LM74 is available in the 8-pin SOIC package as well as an 5-Bump DSBGA package please refer to LM74 data sheet for detailed specifictions pertaining to the packaged parts.

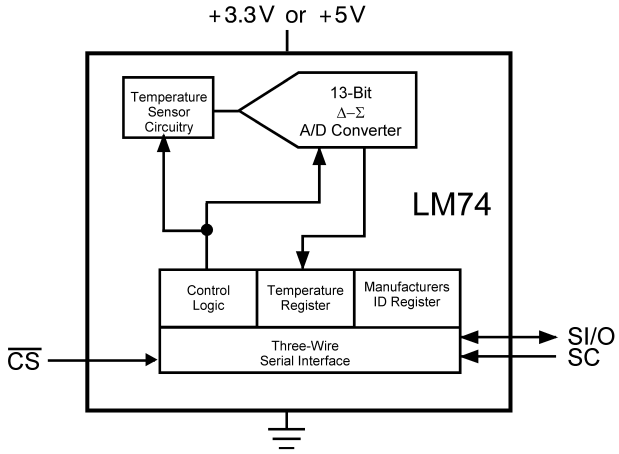
The LM74A has 12-bit plus sign temperature resolution (0.0625°C per LSB) while operating over a temperature range of −40°C to +150°C. The LM74A-5 MDA accuracy of ±3.5°C is specified over a temperature range of 0°C to +150°C.

The LM74A's 4.5V to 5.5V or 3.0V to 3.6V supply voltage range, low supply current and simple SPI interface make it ideal for a wide range of applications. These include thermal management and protection applications in hard disk drives, printers, electronic test equipment, and office electronics.

Table 1. KEY SPECIFICATIONS

Supply Voltage	LM74A-5	4.5V to 5.5V
	LM74A-3	3.0V to 3.6V
Supply Current	Operating	310µA (typ) 520µA (max)
	Shutdown	8µA (typ)
LM74A-5 MDA	0°C to 140°C	±3.0°C(max)
Temperature Accuracy	140°C to 150°C	±3.5°C(max)

Simplified Block Diagram



Connection Diagram

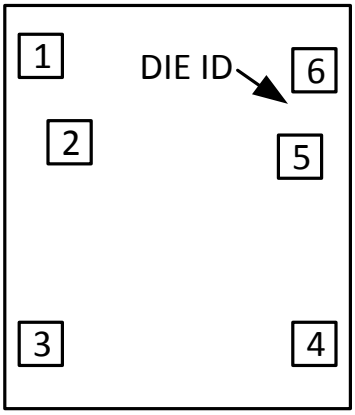


Figure 1. LM74A Bond Pad Layout
Top View
1.40mm x 1.57 mm (55 x 62 mils)

Bond Pad Mechanical Dimensions

Dimensions of bond pad coordinates are in millimeters.

Origin of coordinates: center of die.

X-Direction is in the longitudinal axis of the die.

Coordinates refer to center of Bond Pad.

Pin#	X	Y
1	-0.569 mm	+0.585 mm
2	-0.537 mm	+0.314 mm
3	-0.569 mm	-0.554 mm
4	n/a	n/a
5	+0.537 mm	+0.277 mm
6	+0.569 mm	+0.569 mm
Back		

PIN DESCRIPTIONS

Label	Pin #	Function	Typical Connection
SI/O	1	Slave Input/Output - Serial bus bi-directional data line. Shmitt trigger input.	From and to Controller
SC	2	Slave Clock - Serial bus clock Shmitt trigger input line.	From Controller
GND	3	Power Supply Ground	Ground
NC	4	No Connection	No Connection
$\overline{CS}$	5	Chip Select input.	From Controller
V^+	6	Positive Supply Voltage Input	DC Voltage from 4.5V to 5.5V for the LM74A-5 and 3.0V to 3.6V for the LM74A-3. Bypass with a 0.1 µF ceramic capacitor.
Back	(Backside)		Can go to GND connection

Typical Application

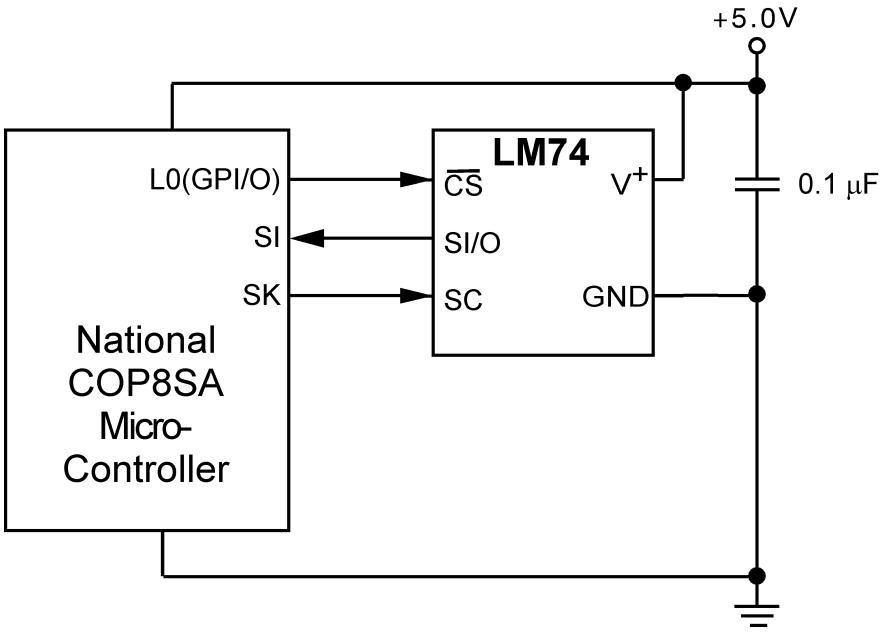


Figure 2. COP Microcontroller Interface

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)

Supply Voltage		−0.3V to 6.0V
Voltage at any Pin		−0.3V to V^+ + 0.3V
Input Current at any Pin (2)		5 mA
Package Input Current (2)		20 mA
Storage Temperature		−65°C to +150°C
ESD Susceptibility (3)	Human Body Mode	2000V
	Machine Model	200V

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions.
(2) When the input voltage (V_I) at any pin exceeds the power supplies (V_I < GND or V_I > +V_S) the current at that pin should be limited to 5 mA. The 20 mA maximum package input current rating limits the number of pins that can safely exceed the power supplies with an input current of 5 mA to four.
(3) Human body model, 100 pF discharged through a 1.5 kΩ resistor. Machine model, 200 pF discharged directly into each pin.

Operating Ratings

Operating Temperature Range		−40°C to +150°C
Specified Temperature Range (1)		T_{MIN} to T_{MAX}
LM74A		-40°C to +150°C
Supply Voltage Range (+V_S)	LM74-5 MDA	+4.5V to +5.5V
	LM74-3 MDA	+3.0V to +3.6V

(1) The life expectancy of the LM74A will be reduced when operating at elevated temperatures.

Temperature-to-Digital Converter Characteristics (1)

Unless otherwise noted, these specifications apply for V^+ = 4.5V to 5.5V for the LM74-5 MDA and V^+ = 3.0V to 3.6V for the LM74-3 MDA. (2). **Boldface limits apply for T_A = T_J = T_{MIN} to T_{MAX};** all other limits T_A = T_J=+25°C, unless otherwise noted.

Parameter	Conditions	Typical (3)	LM74-5 MDA Limits (4)	LM74-3 MDA Limits (4)	Units (Limit)
Temperature Error (2)	T_A = 0°C to +140°C		**±3.0**		°C (max)
	T_A = +140°C to +150°C		**±3.5**		°C (max)
	T_A = -40°C to +150°C			**±5**	°C (max)
Resolution		13			Bits
Temperature Conversion Time	(5)	280	**425**		ms (max)
Quiescent Current	Serial Bus Inactive	310	**520**		µA (max)
	Serial Bus Active	310			µA
	Shutdown Mode, V^+ = 5V	8			µA

(1) For best accuracy, minimize output loading. Higher sink currents can affect sensor accuracy with internal heating. This can cause an error of 0.64°C at full rated sink current and saturation voltage based on junction-to-ambient thermal resistance.
(2) All LM74A parts will function over the V^+ supply voltage range of 3V to 5.5V. The LM74A temperature error specifications for temperature ranges of 0°C to +140°C, 0°C to +150°C and −40°C to +150°C include error induced by power supply variation of ±10% from the nominal value of 5V or 3.3V.
(3) Typicals are at T_A = 25°C and represent most likely parametric norm.
(4) Limits are specified to Texas Instruments' AOQL (Average Outgoing Quality Level).
(5) This specification is provided only to indicate how often temperature data is updated. The LM74A can be read at any time without regard to conversion state (and will yield last conversion result). A conversion in progress will not be interrupted. The output shift register will be updated at the completion of the read and a new conversion restarted.

Logic Electrical Characteristics

DIGITAL DC CHARACTERISTICS

Unless otherwise noted, these specifications apply for V^+ = 4.5V to 5.5V for the LM74-5 MDA and V^+ = 3.0V to 3.6V for the LM74-3 MDA.(1). **Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX};** all other limits $T_A = T_J$=+25°C, unless otherwise noted.

Symbol	Parameter	Conditions	Typical (2)	Limits (3)	Units (Limit)
$V_{IN(1)}$	Logical “1” Input Voltage			**$V^+ \times 0.7$** **$V^+ + 0.3$**	V (min) V (max)
$V_{IN(0)}$	Logical “0” Input Voltage			**−0.3** **$V^+ \times 0.3$**	V (min) V (max)
	Input Hysteresis Voltage	V^+ = 4.5V to 5.5V	0.8	**0.33**	V (min)
$I_{IN(1)}$	Logical “1” Input Current	$V_{IN} = V^+$	0.005	**3.0**	µA (max)
$I_{IN(0)}$	Logical “0” Input Current	V_{IN} = 0V	−0.005	**−3.0**	µA (min)
C_{IN}	All Digital Inputs		20		pF
V_{OH}	High Level Output Voltage	I_{OH} = −400 µA		**$V^+ \times 0.7$**	V (min)
V_{OL}	Low Level Output Voltage	I_{OL} = +2 mA		**0.4**	V (max)
$I_{O\_TRI\text{-}STATE}$	TRI-STATE Output Leakage Current	V_O = GND $V_O = V^+$		**−1** **+1**	µA (min) µA (max)

(1) All LM74A parts will function over the V^+ supply voltage range of 3V to 5.5V. The LM74A temperature error specifications for temperature ranges of 0°C to +140°C, 0°C to +150°C and −40°C to +150°C include error induced by power supply variation of ±10% from the nominal value of 5V or 3.3V.
(2) Typicals are at T_A = 25°C and represent most likely parametric norm.
(3) Limits are specified to Texas Instruments' AOQL (Average Outgoing Quality Level).

Serial Bus Digital Switching Characteristics

Unless otherwise noted, these specifications apply for V^+ = 4.5V to 5.5V for the LM74-5 MDA and V^+ = 3.0V to 3.6V for the LM74-3 MDA.(1). **Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX};** all other limits $T_A = T_J$=+25°C, unless otherwise noted.

Symbol	Parameter	Conditions	Typical (2)	Limits (3)	Units (Limit)
t_1	SC (Clock) Period			**0.16** DC	µs (min) (max)
t_2	$\overline{CS}$ Low to SC (Clock) High Set-Up Time			**100**	ns (min)
t_3	$\overline{CS}$ Low to Data Out (SO) Delay			**70**	ns (max)
t_4	SC (Clock) Low to Data Out (SO) Delay			**100**	ns (max)
t_5	$\overline{CS}$ High to Data Out (SO) TRI-STATE			**200**	ns (max)
t_6	SC (Clock) High to Data In (SI) Hold Time			**50**	ns (min)
t_7	Data In (SI) Set-Up Time to SC (Clock) High			**30**	ns (min)

(1) All LM74A parts will function over the V^+ supply voltage range of 3V to 5.5V. The LM74A temperature error specifications for temperature ranges of 0°C to +140°C, 0°C to +150°C and −40°C to +150°C include error induced by power supply variation of ±10% from the nominal value of 5V or 3.3V.
(2) Typicals are at T_A = 25°C and represent most likely parametric norm.
(3) Limits are specified to Texas Instruments' AOQL (Average Outgoing Quality Level).

Timing Diagrams

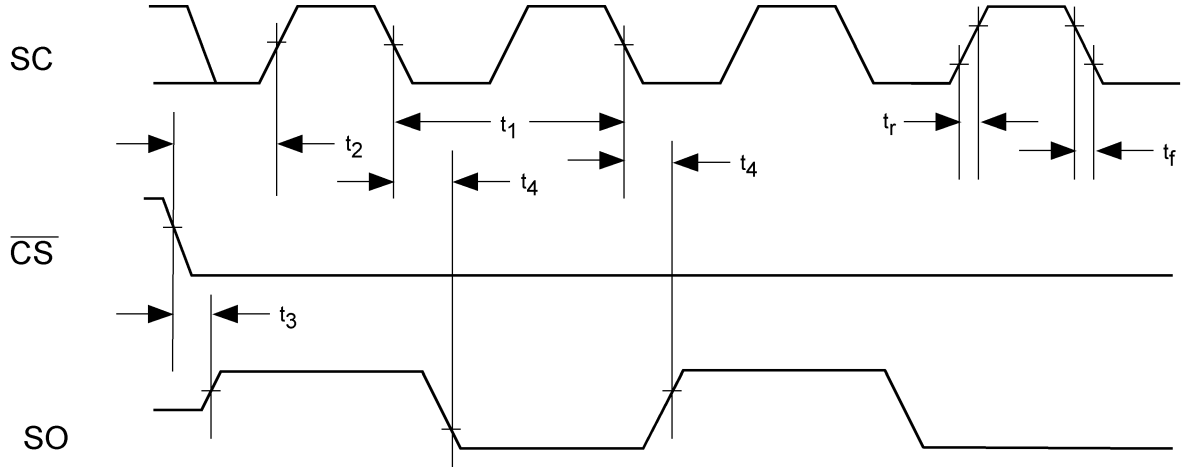


Figure 3. Data Output Timing Diagram

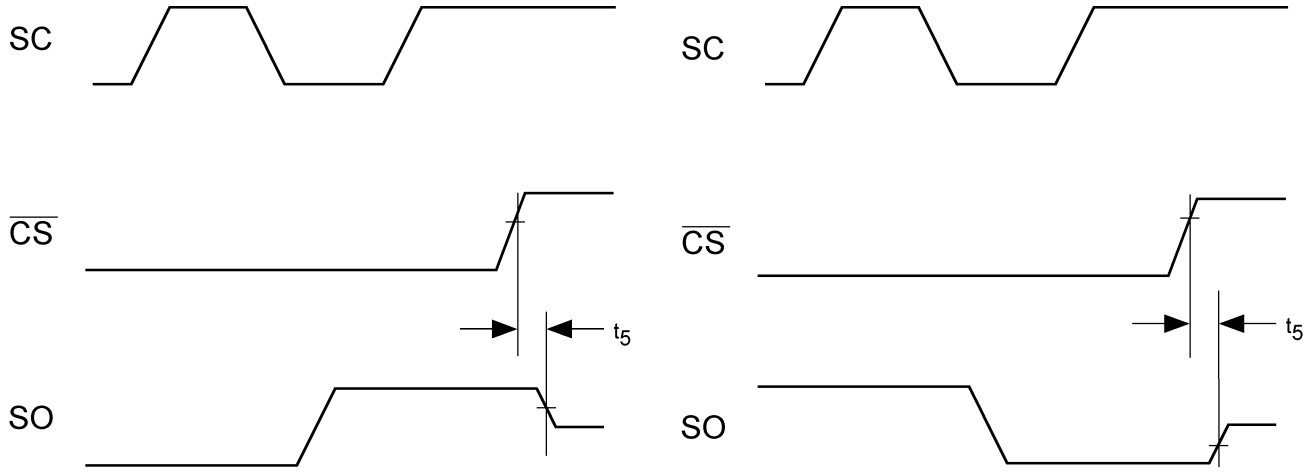


Figure 4. TRI-STATE Data Output Timing Diagram

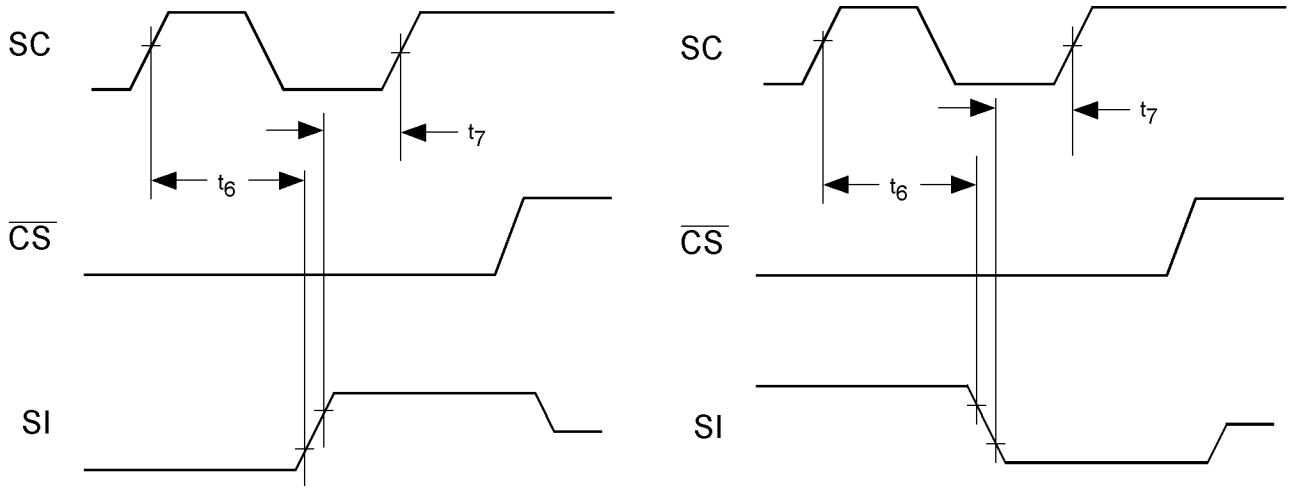


Figure 5. Data Input Timing Diagram

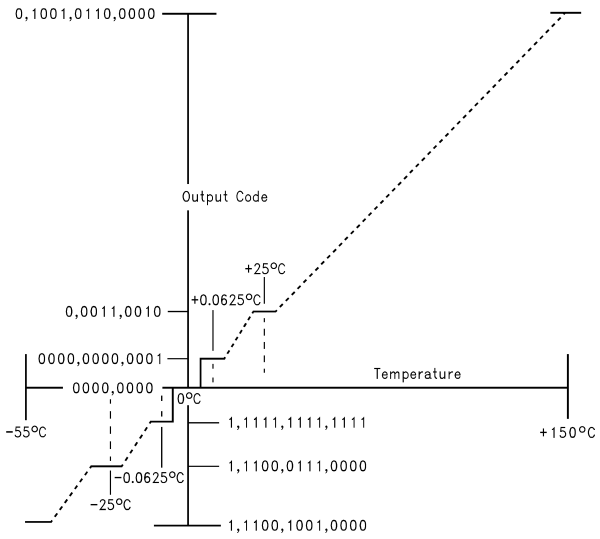
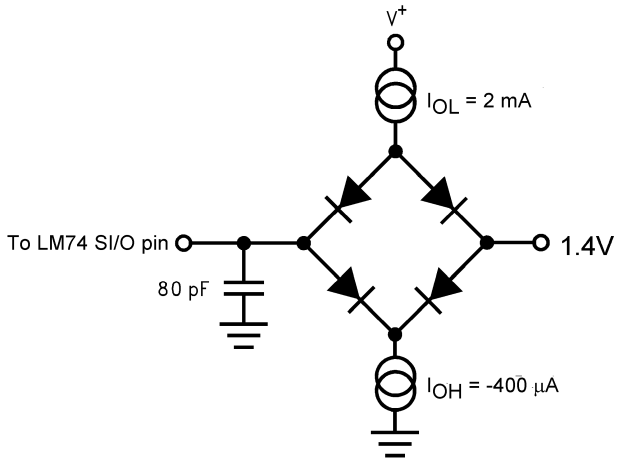


Figure 6. Temperature-to-Digital Transfer Function (Non-linear scale for clarity)

TRI-STATE Test Circuit



Typical Performance Characteristics

Average Power-On Reset Voltage vs Temperature

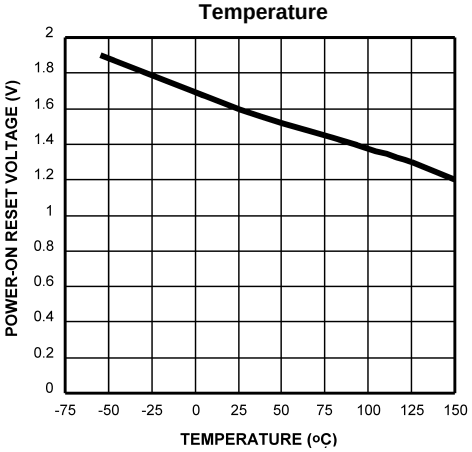


Figure 7.

Static Supply Current vs Temperature

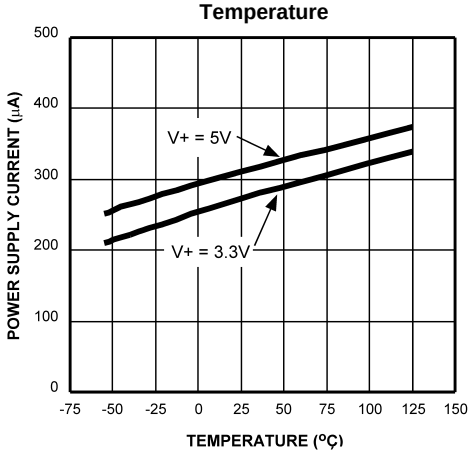


Figure 8.

Temperature Error

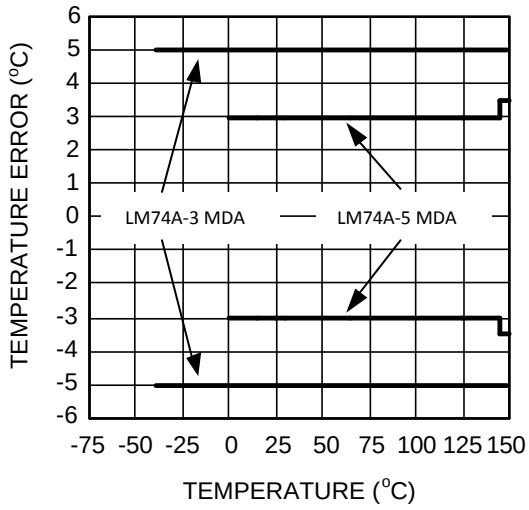


Figure 9.

FUNCTIONAL DESCRIPTION

The LM74A temperature sensor incorporates a band-gap type temperature sensor and 12-bit plus sign ΔΣ ADC (Delta-Sigma Analog-to-Digital Converter). Compatibility of the LM74's three wire serial interface with SPI and MICROWIRE allows simple communications with common microcontrollers and processors. Shutdown mode can be used to optimize current drain for different applications. A Manufacture's/Device ID register identifies the LM74A as National Semiconductor product.

POWER UP AND POWER DOWN

The LM74A always powers up in a known state. The power up default condition is continuous conversion mode. Immediately after power up the LM74A will output an erroneous code until the first temperature conversion has completed.

When the supply voltage is less than about 1.6V (typical), the LM74A is considered powered down. As the supply voltage rises above the nominal 1.6V power up threshold, the internal registers are reset to the power up default state described above.

SERIAL BUS INTERFACE

The LM74A operates as a slave and is compatible with SPI or MICROWIRE bus specifications. Data is clocked out on the falling edge of the serial clock (SC), while data is clocked in on the rising edge of SC. A complete transmit/receive communication will consist of 32 serial clocks. The first 16 clocks comprise the transmit phase of communication, while the second 16 clocks are the receive phase.

When $\overline{CS}$ is high SI/O will be in TRI-STATE. Communication should be initiated by taking chip select ($\overline{CS}$) low. This should not be done when SC is changing from a low to high state. Once $\overline{CS}$ is low the serial I/O pin (SI/O) will transmit the first bit of data. The master can then read this bit with the rising edge of SC. The remainder of the data will be clocked out by the falling edge of SC. Once the 14 bits of data (one sign bit, twelve temperature bits and 1 high bit) are transmitted the SI/O line will go into TRI-STATE. $\overline{CS}$ can be taken high at any time during the transmit phase. If $\overline{CS}$ is brought low in the middle of a conversion the LM74A will complete the conversion and the output shift register will be updated after $\overline{CS}$ is brought back high.

The receive phase of a communication starts after 16 SC periods. $\overline{CS}$ can remain low for 32 SC cycles. The LM74A will read the data available on the SI/O line on the rising edge of the serial clock. Input data is to an 8-bit shift register. The part will detect the last eight bits shifted into the register. The receive phase can last up to 16 SC periods. All ones must be shifted in order to place the part into shutdown. A zero in any location will take the LM74A out of shutdown. The following codes should only be transmitted to the LM74A:

- 00 hex
- 01 hex
- 03 hex
- 07 hex
- 0F hex
- 1F hex
- 3F hex
- 7F hex
- FF hex

Any others may place the part into a Test Mode. Test Modes are used by Texas Instruments to thoroughly test the function of the LM74A during production testing. Only eight bits have been defined above since only the last eight transmitted are detected by the LM74A, before $\overline{CS}$ is taken HIGH.

The following communication can be used to determine the Manufacturer's/Device ID and then immediately place the part into continuous conversion mode. With $\overline{CS}$ continuously low:

- Read 16 bits of temperature data
- Write 16 bits of data commanding shutdown
- Read 16 bits of Manufacture's/Device ID data
- Write 8 to 16 bits of data commanding Conversion Mode
- Take $\overline{CS}$ HIGH.

Note that 250 ms will have to pass for a conversion to complete before the LM74A actually transmits temperature data.

TEMPERATURE DATA FORMAT

Temperature data is represented by a 13-bit, two's complement word with an LSB (Least Significant Bit) equal to 0.0625°C:

Temperature	Digital Output	
	Binary	Hex
+150°C	0100 1011 0000 0111	4B 07h
+125°C	0011 1110 1000 0111	3E 87h
+25°C	0000 1100 1000 0111	0B 87h
+0.0625°C	0000 0000 0000 1111	00 0Fh
0°C	0000 0000 0000 0111	00 07h
−0.0625°C	1111 1111 1111 1111	FF FFh
−25°C	1111 0011 1000 0111	F3 87h
−55°C	1110 0100 1000 0111	E4 87h
Note: The last two bits are TRI-STATE and depicted as one in the table.		

The first data byte is the most significant byte with most significant bit first, permitting only as much data as necessary to be read to determine temperature condition. For instance, if the first four bits of the temperature data indicate an overtemperature condition, the host processor could immediately take action to remedy the excessive temperatures.

SHUTDOWN MODE/MANUFACTURER'S ID

Shutdown mode is enabled by writing XX FF to the LM74A as shown in Figure 12. The serial bus is still active when the LM74A is in shutdown. Current draw drops to less than 10 µA between serial communications. When in shutdown mode the LM74A always will output 1000 0000 0000 0XX. This is the manufacturer's/Device ID information. The first 5-bits of the field (1000 0XXX) are reserved for manufacturer's ID.

INTERNAL REGISTER STRUCTURE

The LM74A has three registers, the temperature register, the configuration register and the manufacturer's/device identification register. The temperature and manufacturer's/device identification registers are read only. The configuration register is write only.

Configuration Register

(Selects shutdown or continuous conversion modes):

Table 2. Configuration Register (Write Only):

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
X	X	X	X	X	X	X	X	Shutdown							

D0–D15 set to XX FF hex enables shutdown mode.

D0–D15 set to 00 00 hex sets Continuous conversion mode.

NOTE

Setting D0-D15 to any other values may place the LM70 into a manufacturer's test mode, upon which the LM74A will stop responding as described. These test modes are to be used for Texas Instruments production testing only. See SERIAL BUS INTERFACE for a complete discussion.

Temperature Register

Table 3. Configuration Register (Read Only):

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
MSB	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	LSB	1	X	X

D0–D1: Undefined. TRI-STATE will be output on SI/0.

D2: Always set high.

D3–D15: Temperature Data. One LSB = 0.0625°C. Two's complement format.

Manufacturer's/Device Id Register

Table 4. Manufacturer's/Device Id Register (Read Only):

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
1	0	0	0	0	0	0	0	0	0	0	0	0	0	X	X

D0–D1: Undefined. TRI-STATE will be output on SI/0.

D2–D15: Manufacturer's/Device ID Data. This register is accessed whenever the LM74A is in shutdown mode.

TEST CIRCUIT DIAGRAMS

Serial Bus Timing Diagrams

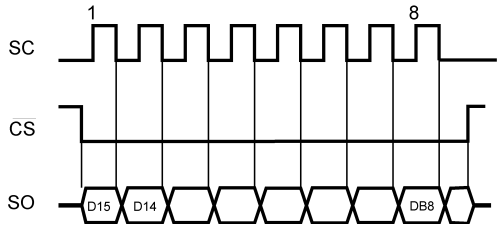


Figure 10. a) Reading Continuous Conversion - Single Eight-Bit Frame

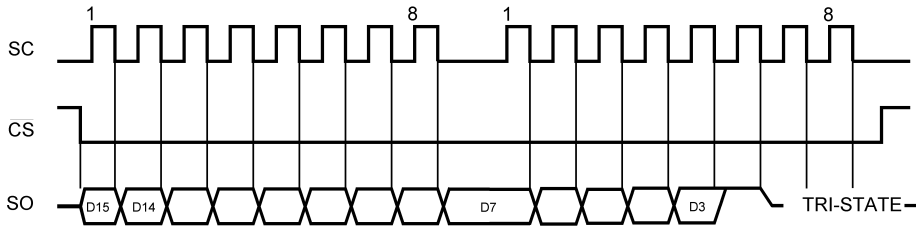


Figure 11. b) Reading Continuous Conversion - Two Eight-Bit Frames

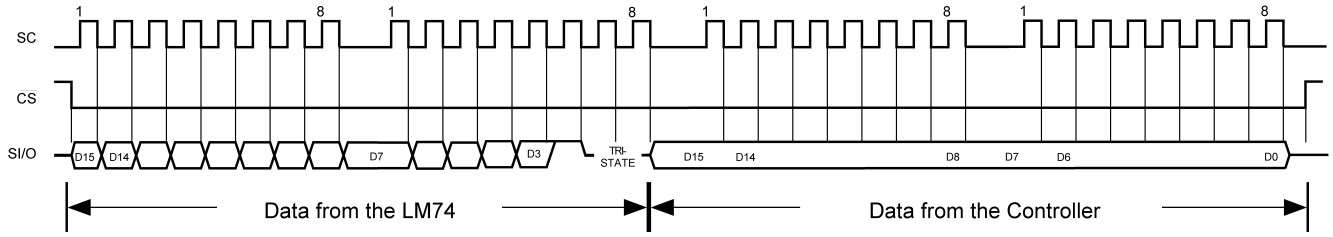


Figure 12. Writing Shutdown Control

Application Hints

LIGHT SENSITIVITY

The LM74A in die form should not be exposed to ultraviolet light. Exposing the LM74A to bright sunlight will not immediatly cause a change in the output reading. Our experiments show that directly exposing the circuit side (pad side) of the die to high intensity (≥ 1mW/cm^2) ultraviolet light, centered at a wavelength of 254nm, for greater than 20 minutes will deprogram the EEPROM cells in the LM74A. Since the EEPROM is used for storing calibration coefficients, the LM74A will function but the temperature accuracy will no longer be as specified. Light can penetrate through the side of the die as well.

Typical Applications

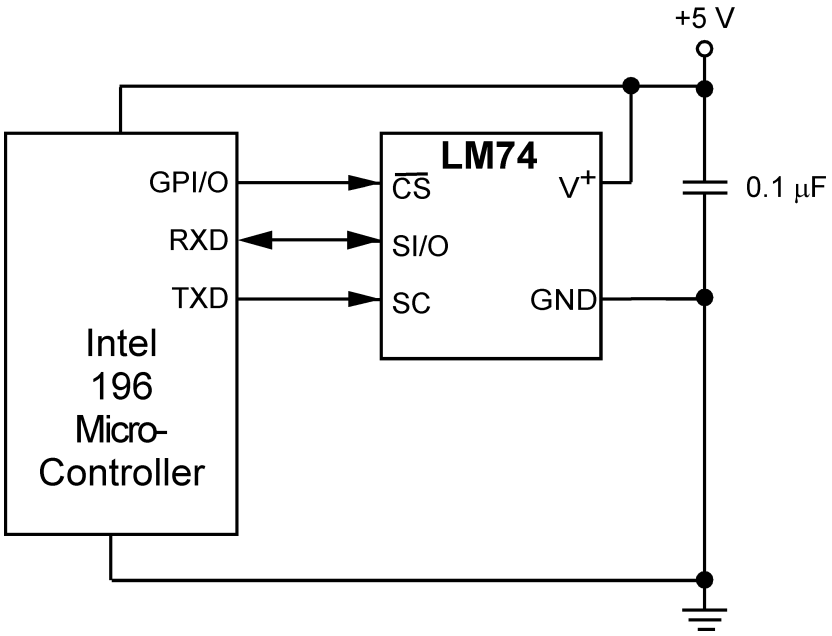


Figure 13. Temperature monitor using Intel 196 processor

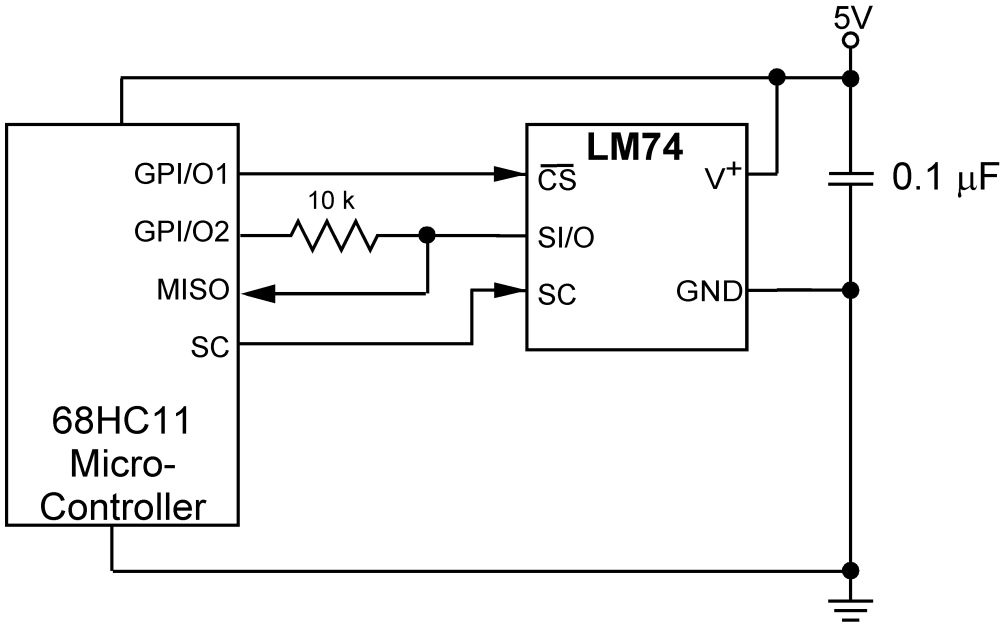
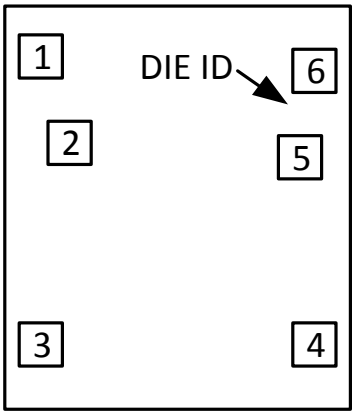


Figure 14. LM74A digital input control using micro-controller's general purpose I/O

Bond Pad Layout



For Bond Pad Mechanical Dimensions see Connection Diagram

Figure 15. Bond Pad Layout
Bare Die
TOP VIEW
1.40mm x 1.57 mm (55 x 62 mils)

REVISION HISTORY

Date	Revision
10/12/2004	1. Added LM74A-3 MDA specifications. 2. Updated order number of LM74A MDA to LM74A-5 MDA.
07/17/2001	Released to web originally.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265